

Programme of Detectors, Electronics and DAQ sub-group meeting
Day-1 (13/02/2012), Venue – Room#4, New TSH Complex, Ground floor
Chair: V.B.Chandratre/B.Satyanarayana

Detectors

| Name | Affiliation | Topic | Start | Duration | End |
|-----------------------|-------------------|---|----------|----------|----------|
| Sumanta Pal | INO student, TIFR | The performance of RPC Stack at TIFR – concluding remarks | 09:30:00 | 00:15:00 | 09:45:00 |
| Moon Moon Devi | INO student, TIFR | Status of the work on development of Multigap RPC in TIFR | 09:45:00 | 00:15:00 | 10:00:00 |
| Raveendrababu Karanam | INO student, IITM | The Development and Characterization of Cosmic Ray Paddles for INO activities in IITM | 10:00:00 | 00:15:00 | 10:15:00 |
| Salim, Mohammed | AMU | Simulation studies of INO RPC | 10:15:00 | 00:15:00 | 10:30:00 |
| Dogra, Sunil | DU | RPC R&D activities at Delhi Univ. | 10:30:00 | 00:15:00 | 10:45:00 |
| Varchaswi Kashyap | INO student, BARC | Characterizing the of cosmic hodoscope at NPD | 10:45:00 | 00:15:00 | 11:00:00 |
| | | Tea break | 11:00:00 | 00:15:00 | 11:15:00 |
| Nayana Majumdar | SINP | The effects of surface topography on charge induced in a Bakelite RPC | 11:15:00 | 00:20:00 | 11:35:00 |
| Manas Bhuyan | TIFR | RPC gas optimisation studies | 11:35:00 | 00:15:00 | 11:50:00 |
| S.D.Kalmani | TIFR | New gas recycling system | 11:50:00 | 00:15:00 | 12:05:00 |
| S.D.Kalmani | TIFR | Industrial interface and consultancy | 12:05:00 | 00:15:00 | 12:20:00 |
| Piyush Verma | TIFR | Integration issues | 12:20:00 | 00:15:00 | 12:35:00 |
| R.R.Shinde | TIFR | Background radiation studies using demo RPC | 12:35:00 | 00:10:00 | 12:45:00 |
| V.K.Bhandari | PU | Status of RPC work at PU | 12:45:00 | 00:15:00 | 13:00:00 |

Electronics & DAQ

| | | | | | |
|-------------------------------|------------|--|----------|----------|----------|
| B.Satyanarayana | TIFR | Overview and status | 14:00:00 | 00:30:00 | 14:30:00 |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC | 14:30:00 | 00:15:00 | 14:45:00 |
| CMEMS | BARC | FE chip upgrade work | 14:45:00 | 00:15:00 | 15:00:00 |
| Mandar Saraf | TIFR | RPC-DAQ module | 15:00:00 | 00:20:00 | 15:20:00 |
| CMEMS | BARC | Status of TDC design | 15:20:00 | 00:15:00 | 15:35:00 |
| B.Satyanarayana | TIFR | Report on IITM activities (Based on Nagendra's report) | 15:35:00 | 00:15:00 | 15:50:00 |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues | 15:50:00 | 00:15:00 | 16:05:00 |
| | | Tea break | 16:05:00 | 00:15:00 | 16:20:00 |
| S.S.Upadhyaya+B.K.Nagesh | TIFR | Data interface schemes | 16:20:00 | 00:15:00 | 16:35:00 |
| P.Nagaraj | TIFR | Networking scheme | 16:35:00 | 00:15:00 | 16:50:00 |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies | 16:50:00 | 00:15:00 | 17:05:00 |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies | 17:05:00 | 00:10:00 | 17:15:00 |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues | 17:15:00 | 00:10:00 | 17:25:00 |
| ECIL group | ECIL | Status report | 17:25:00 | 00:10:00 | 17:35:00 |
| | | Discussion | 17:35:00 | 00:25:00 | 18:00:00 |

News from RPC2012

**SPECIAL MENTION AWARD TO
SUDESHNA DAS GUPTA**

for her paper titled

***PROPOSED TRIGGER SCHEME FOR THE ICAL
DETECTOR OF INDIA-BASED NEUTRINO
OBSERVATORY***

Let us congratulate her for her good work

ICAL Electronics:

miles travelled; milestones to reach

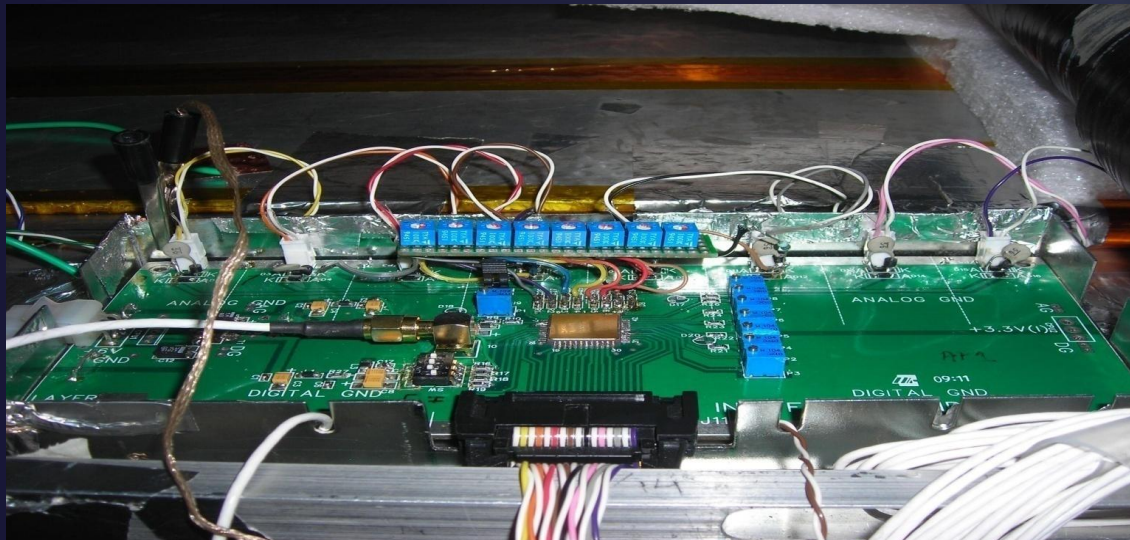
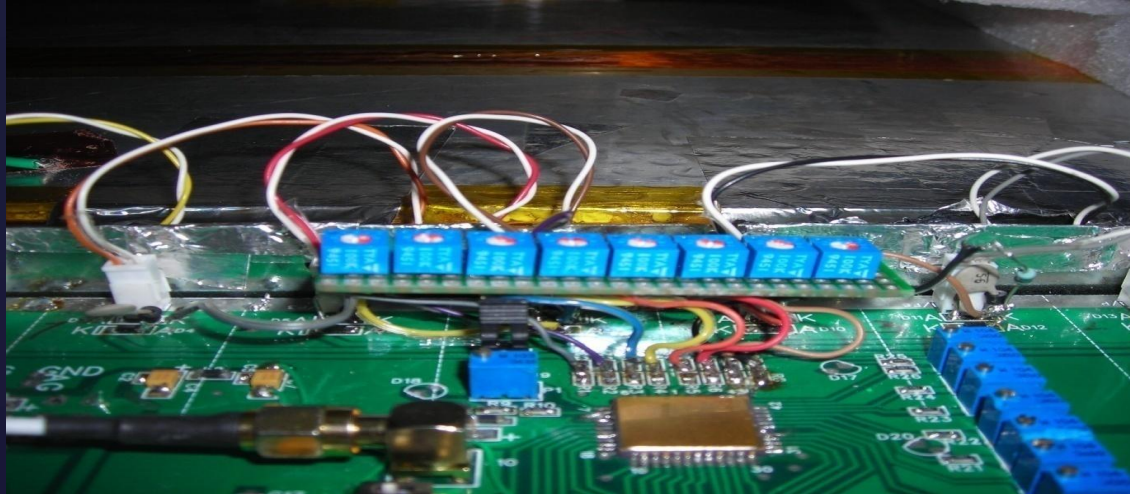
B.Satyanarayana [bsn@tifr.res.in], TIFR, Mumbai

INO Collaboration Meeting, BARC, Mumbai, February 13-15, 2012

Work in progress and action plan

- ❖ Study of amplifier gain and buffer output signal linearity using external pulser
- ❖ Detailed study of threshold adjustment and its stability
- ❖ Try finer threshold adjustment by connecting a $100\text{K}\Omega$ resistor to either side of $P2$ trim-pot (which is $100\text{K}\Omega$)
- ❖ Calibration of threshold for RPC using noise rate and efficiency parameters
- ❖ Integration of front-end board with RPC stack at TIFR
- ❖ Revision of the chip
 - Solve instability problem while the multiplexer is turned on
 - Separate chips for positive and negative inputs as well as amplifier and discriminator might anyway solve this problem

Tale of two FE boards AP1, AP2



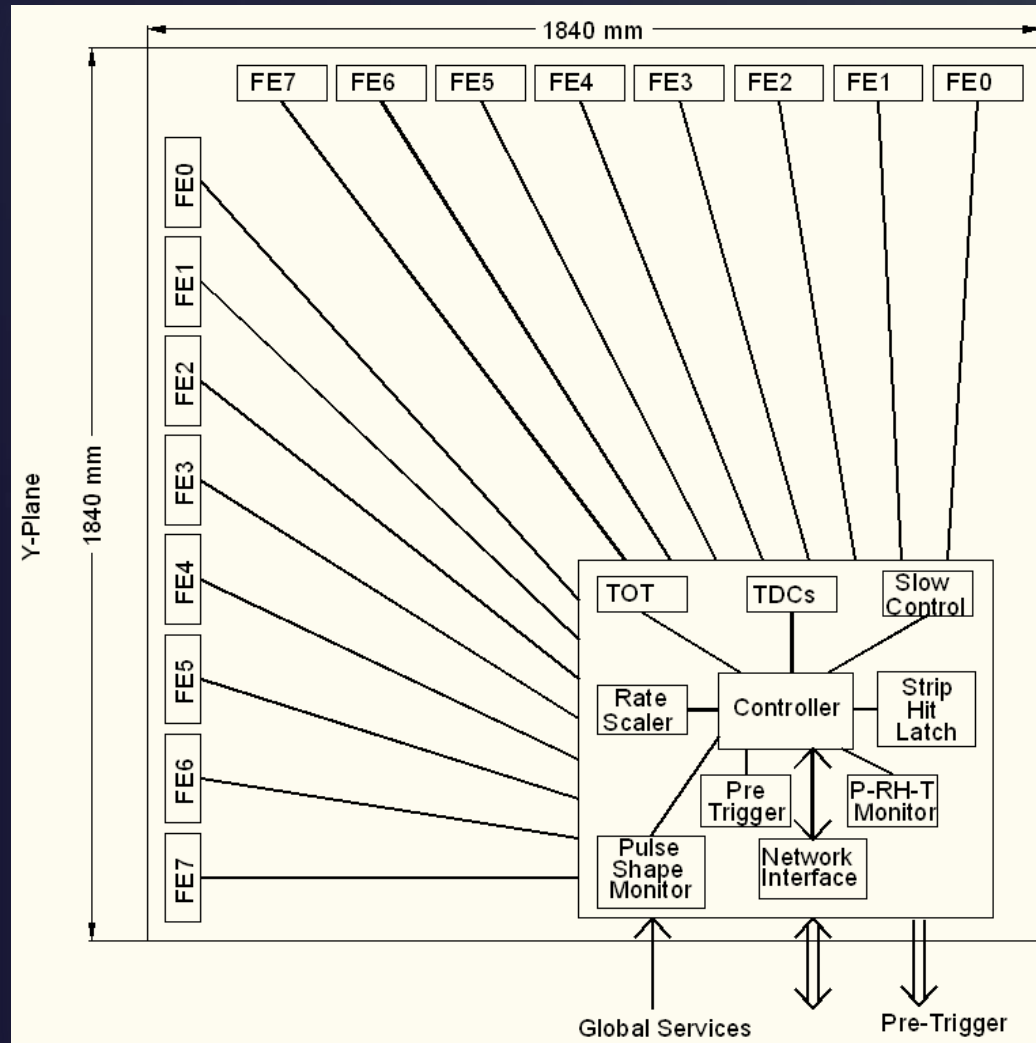
Tests of two FE boards on RPCs

- ❖ Minimum threshold values possible with AP2 and AP1 boards is at $V_{38}=1.650\text{V}$. So the effective threshold is $\sim 250\text{mV}$.
- ❖ Obtained stable noise rates with both boards.
- ❖ Noise rates with HMC based preamplifier is double to those obtained with AP2.
- ❖ Efficiency with AP2 board is about half compared to what was obtained with HMC based board.
- ❖ Operating gain about $4\text{mV}/\mu\text{A}$ as against the design value $8\text{mV}/\mu\text{A}$?
- ❖ Design revisions by the CMEMS group; ready for a second iteration production?

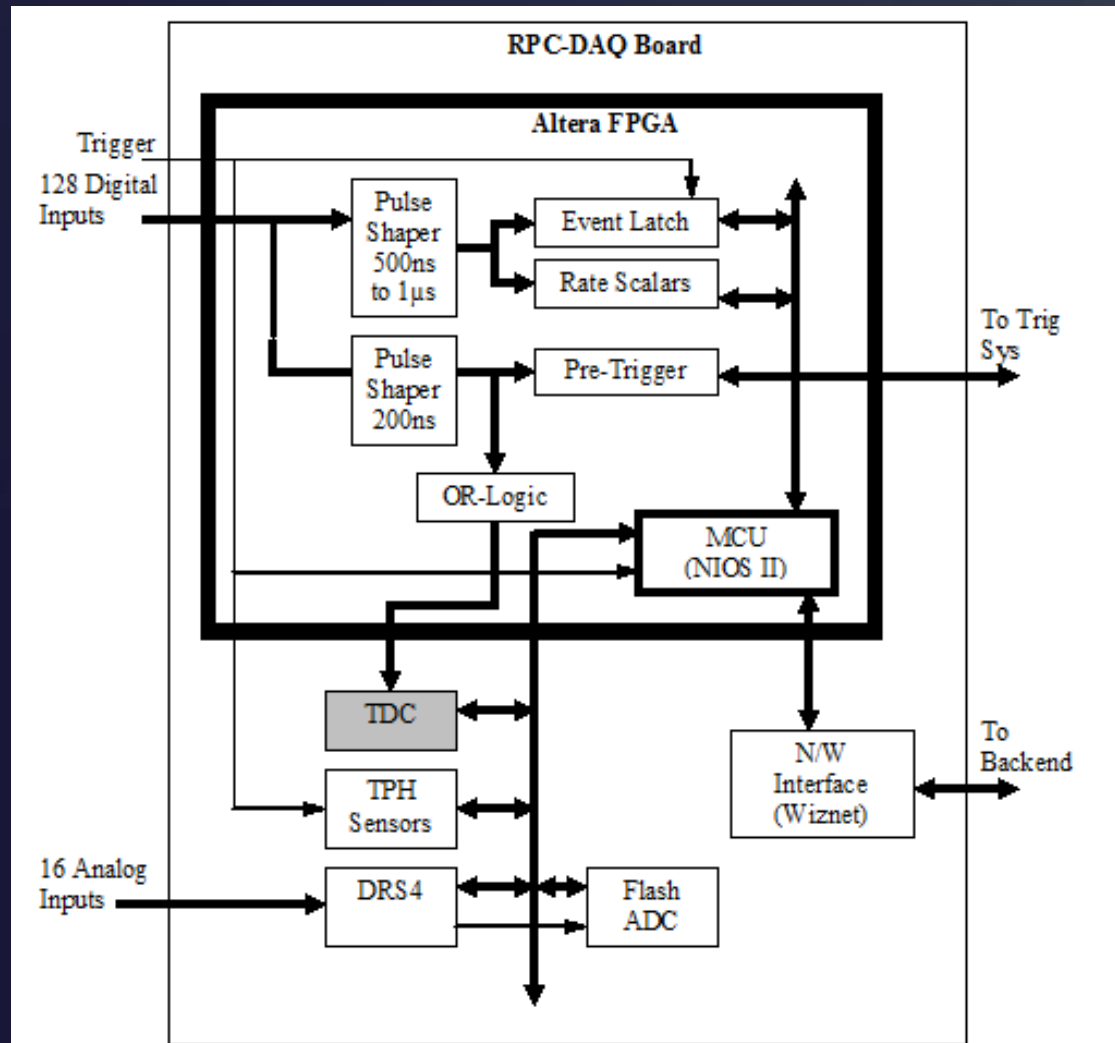
Presentations to follow

| | | |
|-------------------------------|------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhyaya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Functional diagram of RPC-DAQ



Functional diagram of RPC-DAQ



Prototyping of RPC-DAQ module

- ❖ Using IITM designed MSP430 board
- ❖ Digital logic (rate scalers, latches etc.) in FPGA on a trainer kit
- ❖ SPI interface between the two
- ❖ Serial interface between the MSP board and the PC/host
- ❖ Appropriate signal translators for the existing system
- ❖ Will lead to a pilot RPC-DAQ board design

Proof of principle effort (RPC-DAQ)

- ❖ Can be tested today on the RPC stacks
- ❖ Front-end board with the current board's form-factor, but using ASICs
- ❖ RPC-DAQ board with:
 - TDC
 - Waveform sampler
 - Strip-hit latch and rate monitor
 - Controller + data transreceiver
 - Firmware for the above
 - Pre-trigger front-end
 - TPH monitoring
 - Pulse width monitoring
 - Front-end control
 - Signal buffering scheme
 - and GP area or ports for accommodating new blocks
- ❖ VME data concentrator module
- ❖ Result: Complete readout chain is tested
- ❖ Can we use this for RPC QC test stands or what?

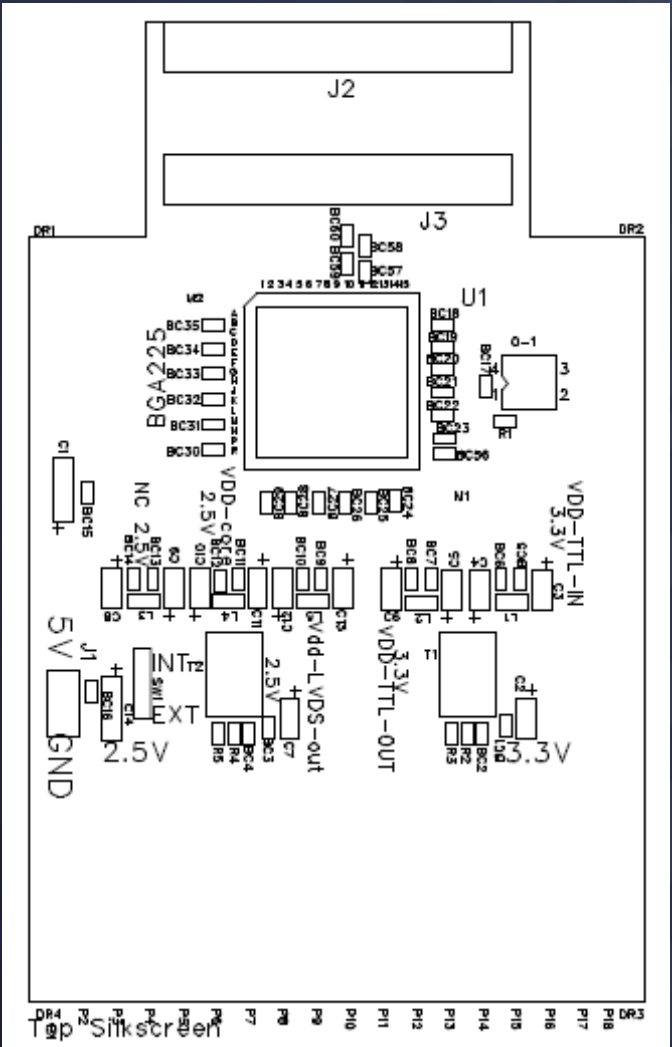
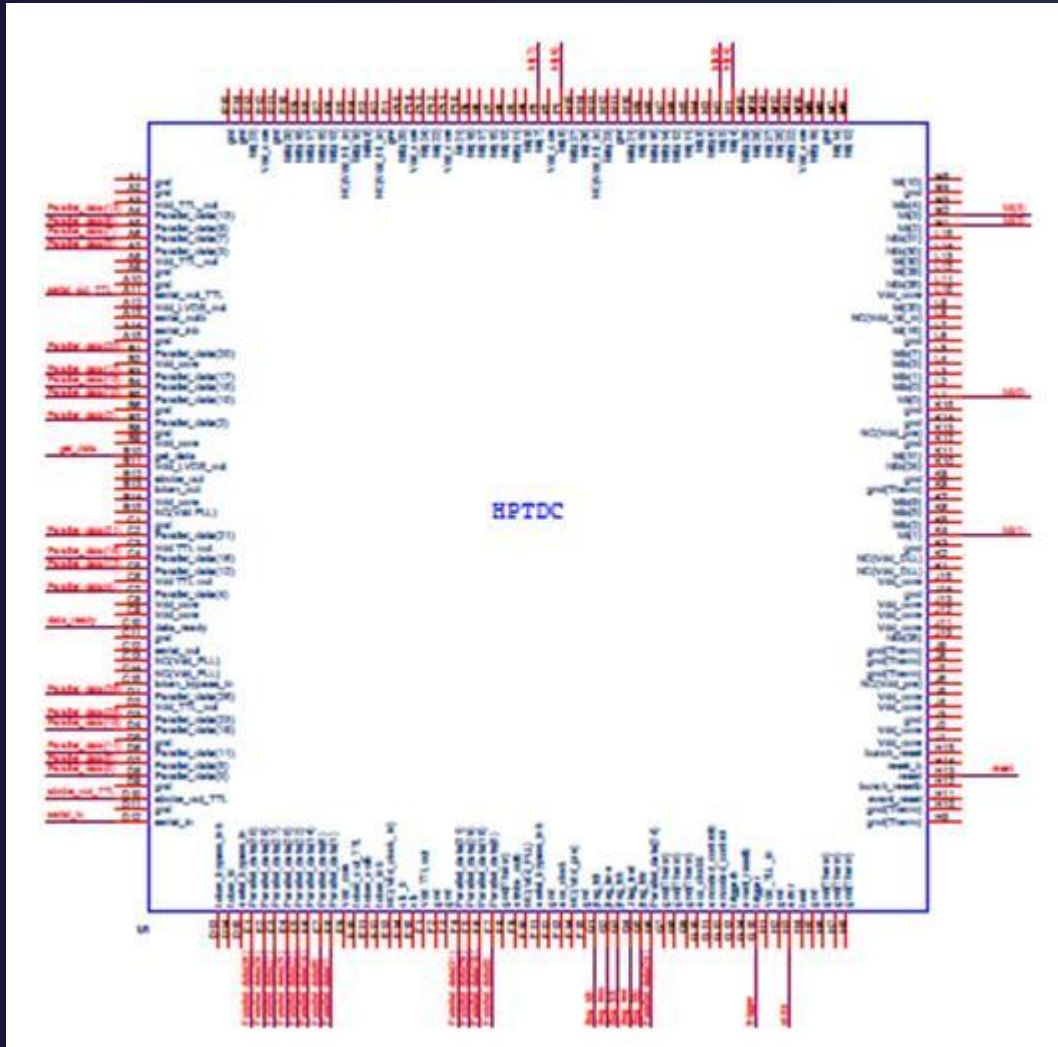
Presentations to follow

| | | |
|-------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Specifications of the ICAL timing device

| Parameter | Specification |
|----------------------------------|---|
| 1. Number of channels | 8 or 16 |
| 2. Least count | 200ps |
| 3. Dynamic range | 2 μ s (essential), 32 μ s (desirable) |
| 4. Number of bits | 14 (essential), 18 (desirable) |
| 5. Type | Common stop |
| 6. Hits | Single hit (essential), multi hit (desirable) |
| 7. Double hit resolution | 5-10ns |
| 8. Readout buffer size | 128 words (maximum) |
| 9. Signal and control inputs | LVDS and LVTTL respectively |
| 10.DNL/INL | 100ps (typical) |
| 11.Power rail | 3.0 to 3.6V (suggested) |
| 12.Control and readout interface | SPI (essential), SPI + parallel (desirable) |

Place-holder for TDC on RPC-DAQ prototype



Presentations to follow

| | | |
|-------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Chip design activities at IIT Madras

- ❖ Front end amplifier (gain ~ 100 , BW $\sim 500\text{MHz}$)
- ❖ Time to digital converter (delay line based, 50ps)
- ❖ Analog memory (64 samples, 2GSPS, 8-bit 10MHz ADC)
- ❖ More on these developments from Anil → Nagendra

Harshit Vaishnav's thesis

In this project, design of a front end circuitry for neutrino detectors is presented. The system consists of a high speed front end amplifier and latching circuitry. A time to digital converter (TDC) is used to measure the time of arrival of the input with respect to a reference start. A delay locked loop is used to stabilize the delays against PVT variations. A phase locked loop is used to generate a high frequency clock from a low frequency input clock. A digital back-end is designed to process the data digitally and to output a serial data stream.

The design is implemented in 0.13 μm CMOS process. The TDC has a resolution of 125 ps and a range of 131 μs . It occupies 0.24 mm^2 area and consumes negligible static power. The DLL occupies 0.12 mm^2 area and consumes a power of 2 mW. The amplifier has a DC gain of 41.5 dB and a bandwidth of 513 MHz and consumes 0.2 mW power. The design will be sent for fabrication in the UMC 0.13 μm CMOS process.

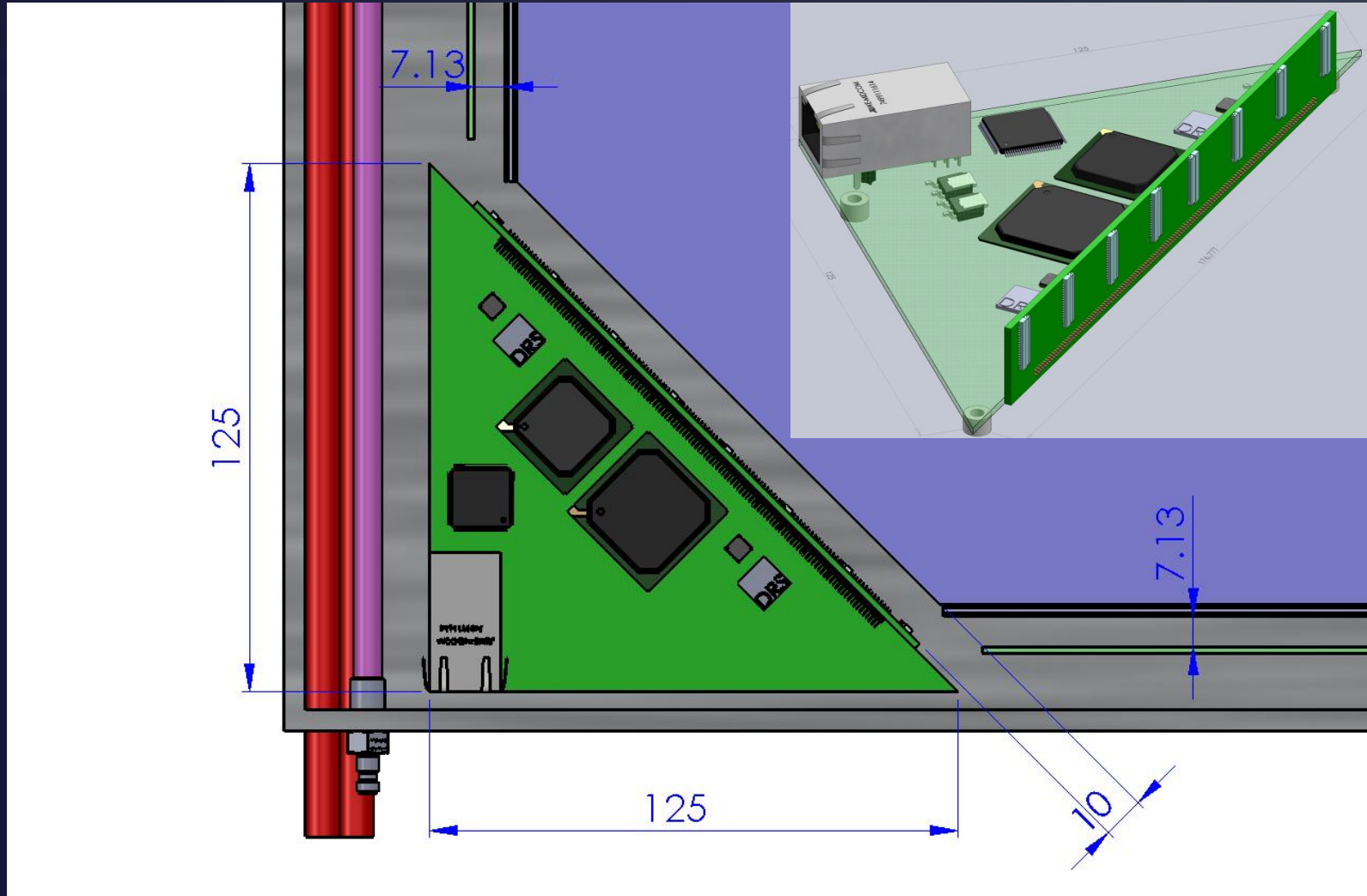
Presentations to follow

| | | |
|-------------------------------|-------------|--|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Integration issues

- ❖ Mounting of electronics on top of RPC is not *liked* – wasting of space/volume
- ❖ Suggestion to mount on the sides
- ❖ Increase the chamfered areas on four corners of the RPC
- ❖ Mount DAQ for two planes (X & Y) and power supplies (LV, HV) in these areas
- ❖ Front-ends to be mounted along the planes
- ❖ Issue of pickup-strips to the front-end solved automatically!
- ❖ Modeling and prototyping in progress
- ❖ Industrial dimensions of glass is helping this scheme

Fighting for an mm in a 132m×26m×20m cavern!



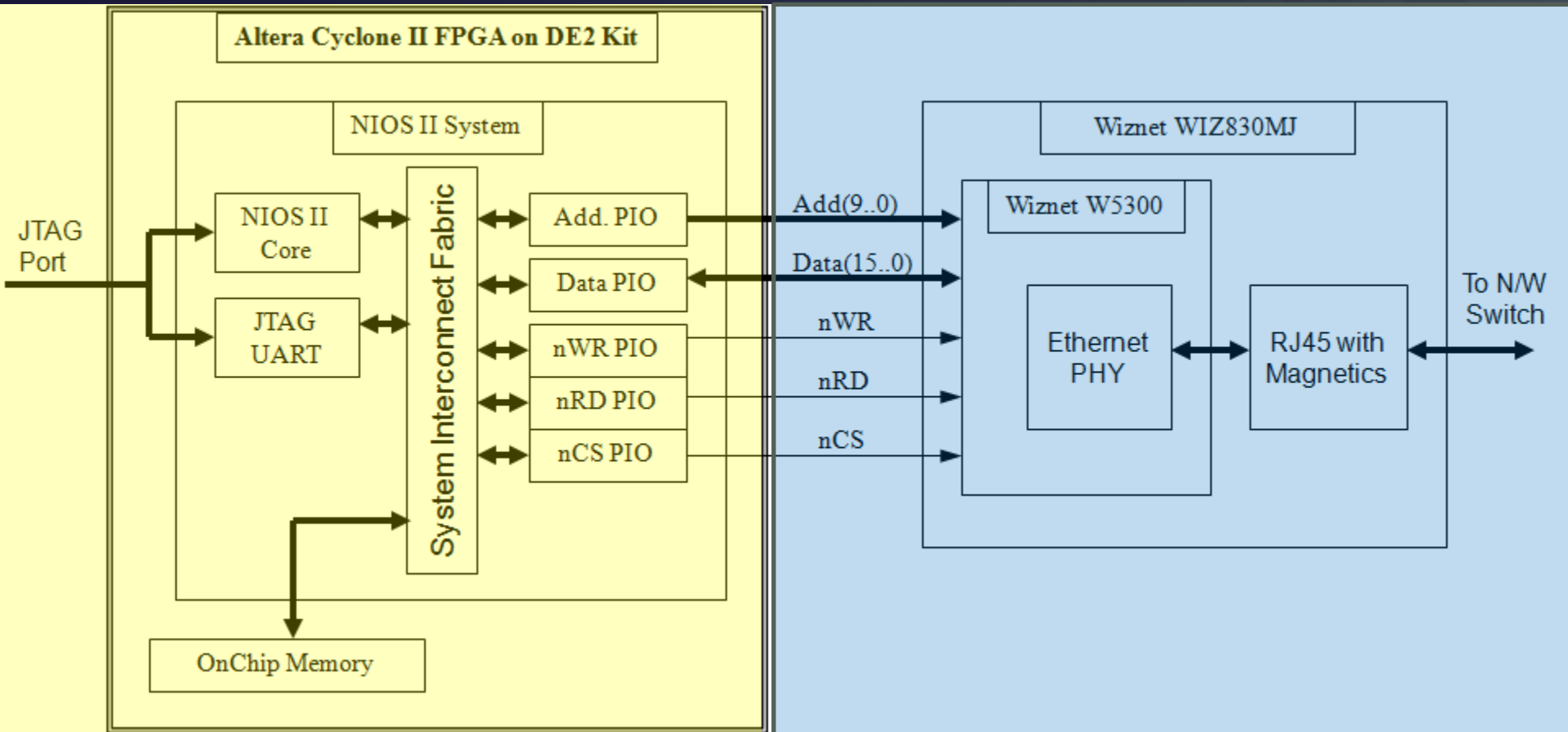
Presentations to follow

| | | |
|----------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Networked DAQ scheme

- ❖ Alternate approach for VME back-end
- ❖ Choose appropriate controller
- ❖ Simplified system design, cabling
- ❖ Speed, switching, protocols

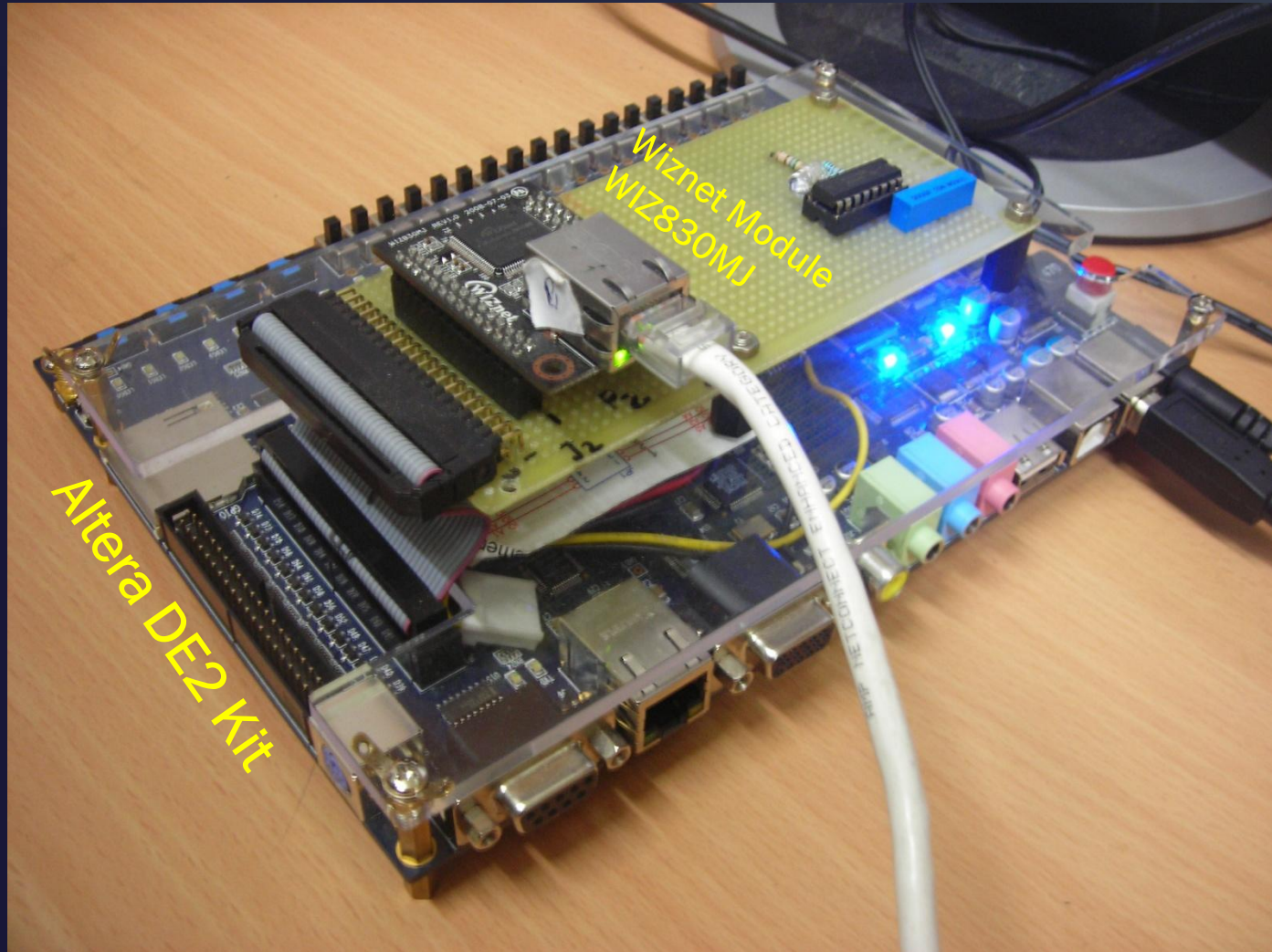
Wiznet to FPGA Interface



Current work on data interface

- ❖ Altera DE2 kit with Cyclone II EP2C35 FPGA
- ❖ FPGA configured with NIOS II system using SOPC Builder a part of Altera Quartus
- ❖ Wiznet W5300 interfaced to NIOS II in port mapped I/O mode
- ❖ Software developed in NIOS II EDS IDE in C
- ❖ Established two way communication between PC and Wiznet test setup.

Wiznet to FPGA Interface



Presentations to follow

| | | |
|---------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhyaya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Event data rates

- ❖ Event Data per Trigger is as follows: (64 strips on each plane of RPC)
- ❖ TDC data = 1 channel for 8 strips and both the edges per hit, up to 4 hits per channel per event = $16 \text{ channels} \times 2 \text{ edges} \times 4 \text{ hits} \times 16 \text{ bits} = 2048 \text{ bits}$
- ❖ Hit data per RPC = 128 bits
- ❖ RPC ID = 32 bits
- ❖ Event ID = 32 bits
- ❖ Time Stamp = 64 bits
- ❖ DRS data = $16 \text{ channels} \times 1000 \text{ samples} \times 16 \text{ bits} = 256000 \text{ bits}$
- ❖ (DRS data comes in event data only if we get summed analog outputs from the preamplifier)
- ❖ Data size per event per RPC
- ❖ With DRS data, $D_R = 2048 + 128 + 32 + 32 + 64 + 256000 = 258,304 \text{ bits}$
- ❖ Without DRS data, $D_R = 2048 + 128 + 32 + 32 + 64 = 2,304 \text{ bits}$
- ❖ **Considering 1Hz trigger rate, Maximum Data Rate at each RPC = 252.25 kbps**
- ❖ Total data size per event across 3 modules
- ❖ With DRS data, $D_T = 258304 \times 28800 = 7,439,155,200 \text{ bits}$ i.e. 6.928 Gbits
- ❖ Without DRS data, $D_T = 2304 \times 28800 = 66,355,200 \text{ bits}$ i.e. 63.28125 Mbits
- ❖ **Considering 1Hz trigger rate, Maximum Data Rate at backend = 6.928 Gbps**

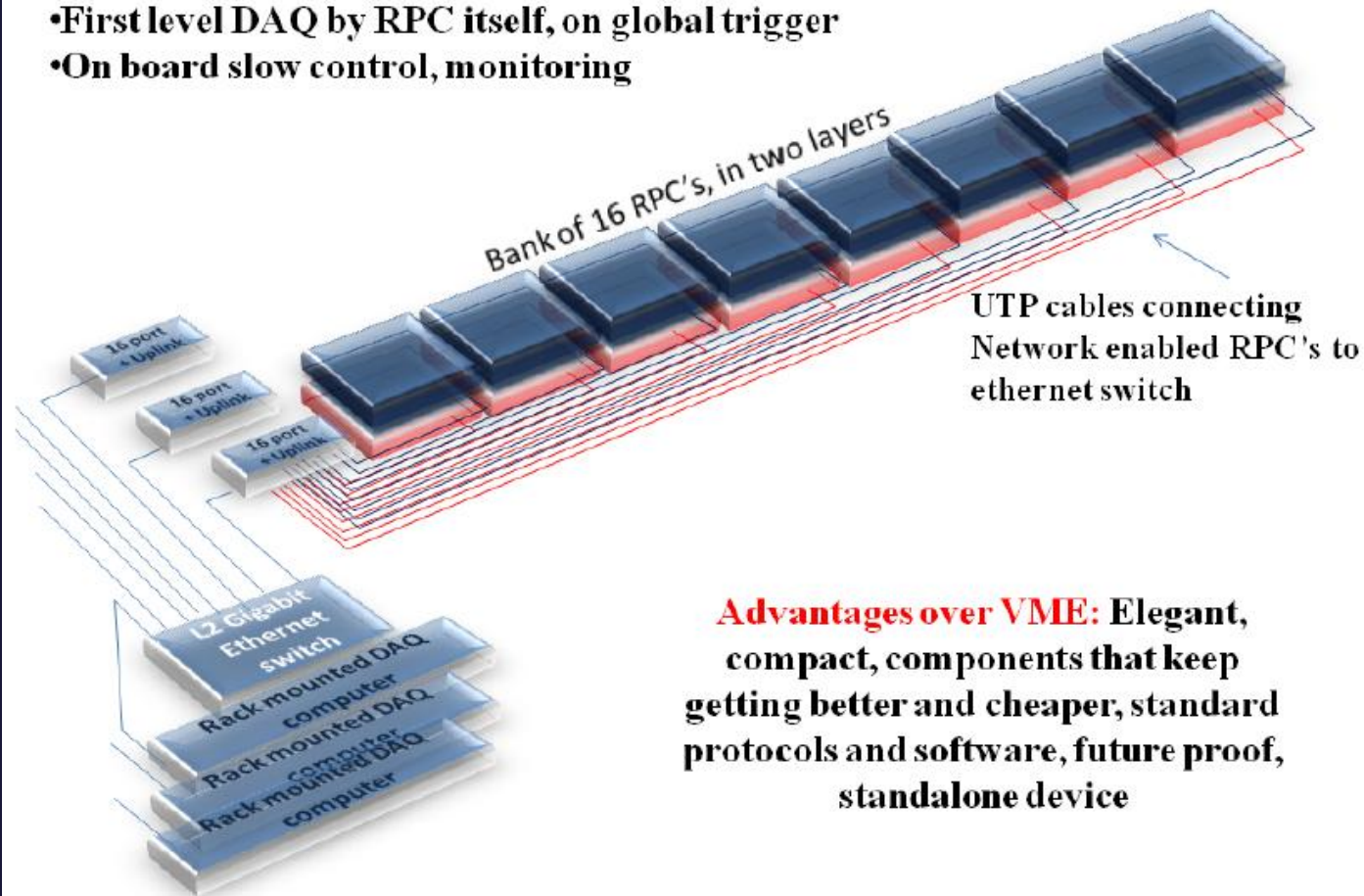
Monitor data rates

- ❖ Monitor Data per 10 seconds
- ❖ We require to monitor 1 pick-up strip per plane per RPC.
- ❖ Monitor Data per strip = 24 bits
- ❖ Channel ID = 8 bits
- ❖ RPC ID = 32 bits
- ❖ Mon Event ID = 32 bits
- ❖ Ambient Sensors' data = 3×16 bits = 48 bits
- ❖ Time Stamp = 64 bits
- ❖ DRS data = 1000 pulses (if noise rate is 100Hz) \times 16 bits \times 100 samples = 1600000 bits
- ❖ (DRS data comes in monitoring data only if we get multiplexed analog outputs from the preamplifier)

- ❖ Data size per 10 seconds RPC
- ❖ With DRS data = $24 + 8 + 32 + 32 + 48 + 64 + 2048 + 1600000 = 1,602,256$ bits
- ❖ Without DRS data = $24 + 8 + 32 + 32 + 48 + 64 + 2048 = 2,256$ bits
- ❖ **Max Data Rate for 10 second monitoring period per RPC = 156.47 kbps**

Networking issues, devices

- RPC's designed as network devices
- Each RPC will have Embedded μ P + Linux + TCP/IP
- First level DAQ by RPC itself, on global trigger
- On board slow control, monitoring



Advantages over VME: Elegant, compact, components that keep getting better and cheaper, standard protocols and software, future proof, standalone device

Presentations to follow

| | | |
|-------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Trigger scheme for ICAL

- ❖ Validation of the trigger schemes
- ❖ Ready to go for implementation
- ❖ Integration issues
 - Segment trigger module positions
 - Pre-trigger signal driving issues
- ❖ Specifications:
 - Coincidence window: 100ns
 - Maximum trigger latency: 1us
 - Singles rate for RPC detector pickup strips: 250 Hz
 - The skew and jitter in arrival instant of the global trigger at different RPCs should be as low possible
- ❖ News: BARC team (Anita Behere *et al*) joined the trigger team for implementation

Trigger implementation

- ❖ Trigger scheme developed and validated
- ❖ Layout of trigger scheme implementation
- ❖ Study of LVDS transmission
- ❖ Conceptual design of the trigger modules
- ❖ FPGA logic development
- ❖ Validation of design concept in FTM

Presentations to follow

| | | |
|-------------------------------|-------------|--|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Role of waveform sampler for ICAL

- ❖ Walk correction of TDC data
- ❖ Leading edge discriminator
- ❖ Time over threshold information
- ❖ Pulse profile, height and width monitoring
- ❖ Remote display of RPC signals

Consolidation of its function

- ❖ Better understood DRS4 – thanks to the *demo RPC* project!
- ❖ Not sure though, if we understood the exact role and hence its exact operation scheme ICAL electronics
- ❖ Do we use in both event and monitoring modes?
- ❖ The above required different front-ends for the analog front-ends
 - Multiplexed analog signal
 - Easier to implement?
 - Timing problem in event mode
 - Summed/ORed analog signal
 - Relatively difficult to implement?
 - No timing issue, hit channel id could be inferred
- ❖ Where is the chip?

Power supply options

- ❖ High voltage (Central scheme)
 - Two options: a channel at 12kV or two channels at $\pm 6\text{kV}$
 - Consider powering 4 RPC with a single HV channel (10 μA current)
 - Cable diameter an integration issues, connectors a cost issue
- ❖ High voltage (Distributed scheme)
 - DC-DCHV converters
 - Each RPC has to be identical to the others
 - Each RPC will have its own DC-HVDC converter for generating HV and LV
- ❖ Low voltage
 - Power budget 25W per RPC
 - How many low voltages?
- ❖ Space for DC-DC converters inside the RPC unit an integration issue
- ❖ Magnetic field
 - Fringe field mostly is below 100 Gauss
 - But some places between 100 and 1000 Gauss
 - Difference between 100 and 1000 Gauss is relevant for the design of the DC-HVDC

Presentations to follow

| | | |
|--------------------------------------|-------------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Software components

- ❖ RPC-DAQ controller firmware
- ❖ Backend online DAQ system
- ❖ Local and remote shift consoles
- ❖ Data packing and archival
- ❖ Event and monitor display panels
- ❖ Event data quality monitors
- ❖ Slow control and monitor consoles
- ❖ Database standards
- ❖ Plotting and analysis software standards
- ❖ OS and development platforms

Software

- ❖ **News:** BARC team (Diwakar, Padmini *et al*) joined the software team
- ❖ **Back-end Data Acquisition and Monitoring System**
 - Event Data Acquisition
 - Periodic Online Monitoring of RPC Parameters
 - Event Data Quality Monitoring
 - Control and Monitoring Console
 - Local and Remote Consoles
- ❖ **Front-end firmware/software will be responsibility of the TIFR group**
- ❖ **Scope for more players (especially physicists)**

Presentations to follow

| | | |
|-------------------------------------|------------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhyaya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Industrial interfaces, services

Presentations to follow

| | | |
|-------------------------------|-------------|---------------------------------------|
| B.Satyanarayana | TIFR | Overview and status |
| Sonal Dhuldhaj | TIFR | FE chip tests with RPC |
| CMEMS group | BARC | FE chip upgrade work |
| Mandar Saraf | TIFR | RPC-DAQ module |
| CMEMS group | BARC | Status of TDC design |
| Nagendra Krishnapura | IITM | Integrated Circuits for the INO |
| Mandar Saraf+Piyush Verma | TIFR | Integration issues |
| S.S.Upadhyaya+B.K.Nagesh | TIFR | Data interface schemes |
| P.Nagaraj | TIFR | Networking scheme |
| Sudeshna Dasgupta | TIFR | Trigger scheme implementation studies |
| B.Satyanarayana+Satyajit Saha | TIFR+ SINP | Power supplies |
| Deepak Samuel+BARC S/W group | TIFR+BARC | Software issues |
| ECIL group | ECIL | Status report |

Priorities and promises

- ❖ ICAL Electronics documentation
- ❖ Delays and Synchronisation scheme
- ❖ Timeline for the 8m×8m engineering model
- ❖ Location of components and their integration issues